Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

Contact us

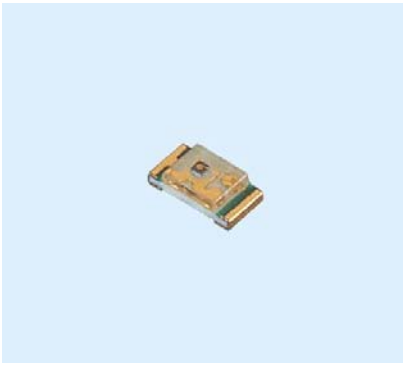
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832
Email & Skype: info@chipsmall.com Web: www.chipsmall.com
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

EVERLIGHT ELECTRONICS CO.,LTD.

Technical Data Sheet

0603 Package Chip LED(0.4mm Height)

19-217/G7C-AL1M2B/3T



Features

- Package in 8mm tape on 7″ diameter reel.
- Compatible with automatic placement equipment.
- Compatible with infrared and vapor phase reflow solder process.
- Mono-color type.
- Pb-free.
- The product itself will remain within RoHS complaint version

Descriptions

- The 19-217 SMD LED is much smaller than lead frame type components, thus enable smaller board size, higher packing density, reduced storage space and finally smaller equipment to be obtained.
- Besides, lightweight makes them ideal for miniature applications. etc.

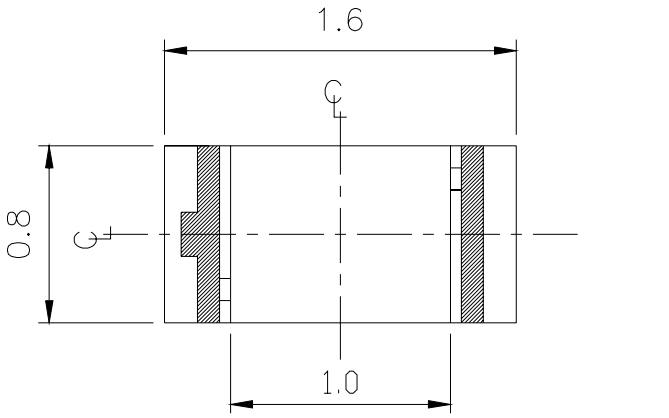
Applications

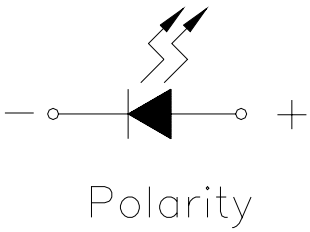
- Backlighting in dashboard and switch.
- Telecommunication: indicator and backlighting in telephone and fax.
- Flat backlight for LCD, switch and symbol.
- General use.

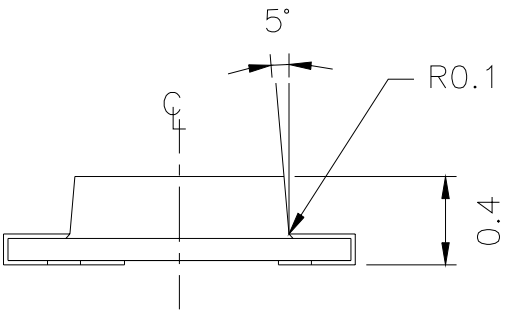
Device Selection Guide

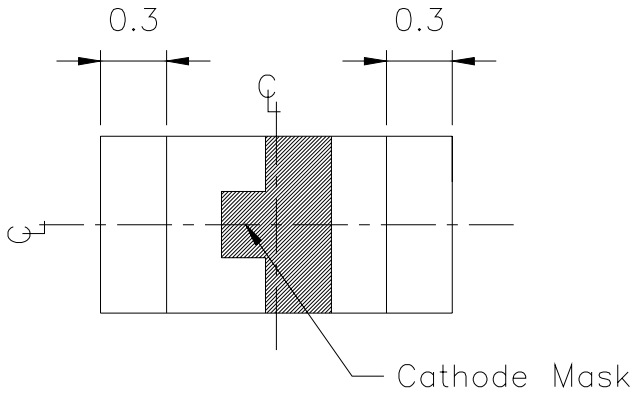
Part No.	Chip Material	Emitted Color	Resin Color
19-217/G7C-AL1M2B/3T	AlGaInP	Brilliant Yellow Green	Water Clear

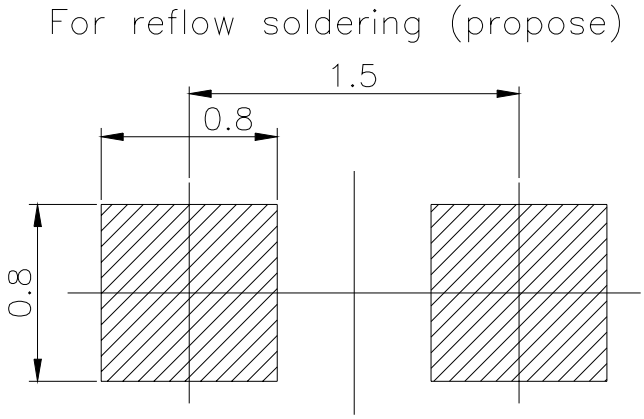
Package Outline Dimensions











Note: The tolerances unless mentioned is ±0.1mm ,Unit

Absolute Maximum Ratings (Ta=25℃)

Parameter	Symbol	Rating	Unit
Reverse Voltage	V_R	5	V
Forward Current	I_F	25	mA
Peak Forward Current (Duty 1/10 @1KHz)	I_{FP}	60	mA
Power Dissipation	Pd	60	mW
Electrostatic Discharge(HBM)	ESD	2000	V
Operating Temperature	Topr	-40 ~ +85	℃
Storage Temperature	Tstg	-40 ~ +90	℃
Soldering Temperature	Tsol	Reflow Soldering : 260 ℃ for 10 sec. Hand Soldering : 350 ℃ for 3 sec.	

Electro-Optical Characteristics (Ta=25℃)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Luminous Intensity	Iv	11.5	-----	28.5	mcd	I_F=20mA
Viewing Angle	2θ 1/2	-----	120	-----	deg	
Peak Wavelength	λ p	-----	575	-----	nm	
Dominant Wavelength	λ d	569.5	-----	577.5	nm	
Spectrum Radiation Bandwidth	△λ	-----	20	-----	nm	
Forward Voltage	V_F	1.75	-----	2.35	V	
Reverse Current	I_R	-----	-----	10	μA	V_R=5V

Notes:

1.Tolerance of Luminous Intensity ±11%

2.Tolerance of Dominant Wavelength ±1nm

3.Tolerance of Forward Voltage ±0.1V

Bin Range Of Dom. Wavelength

Group	Bin	Min	Max	Unit	Condition
A	C16	569.5	571.5	nm	IF=20mA
	C17	571.5	573.5		
	C18	573.5	575.5		
	C19	575.5	577.5		

Bin Range Of Luminous Intensity

Bin	Min	Max	Unit	Condition
L1	11.5	14.5	mcd	IF=20mA
L2	14.5	18.0		
M1	18.0	22.5		
M2	22.5	28.5		

Bin Range Of Forward Voltage

Group	Bin	Min	Max	Unit	Condition
B	0	1.75	1.95	V	IF=20mA
	1	1.95	2.15		
	2	2.15	2.35		

Notes:

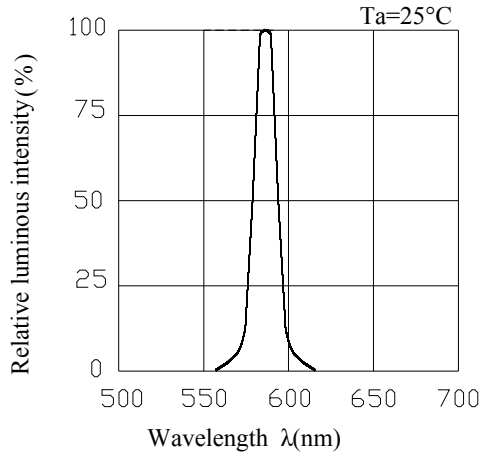
1.ToleLance of Luminous Intensity ±11%

2.ToleLance of Dominant Wavelength ±1nm

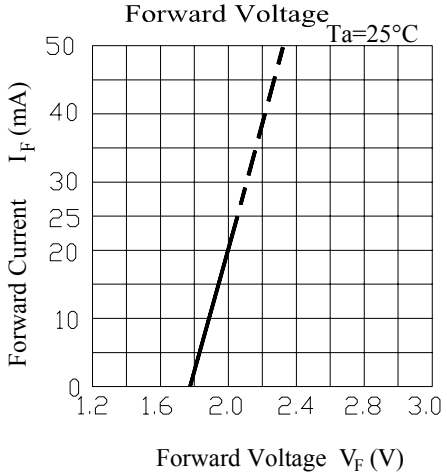
3.ToleLance of FoLwaLd Voltage ±0.1 V

Typical ElectLo-Optical ChaLacteListics CuLves

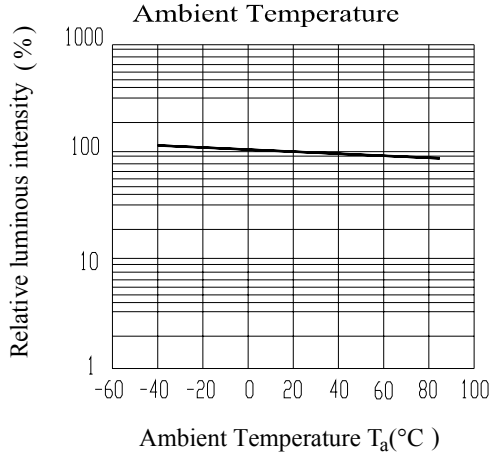
Spectrum Distribution



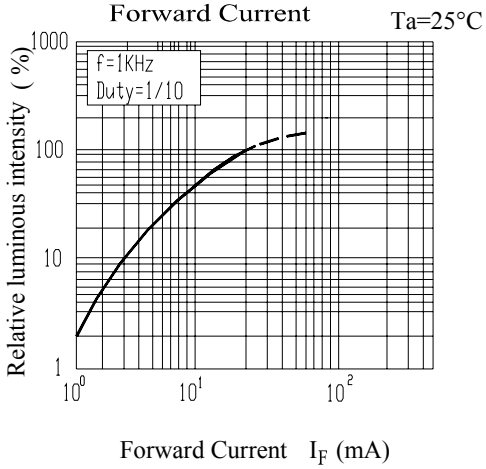
Forward Current vs. Forward Voltage



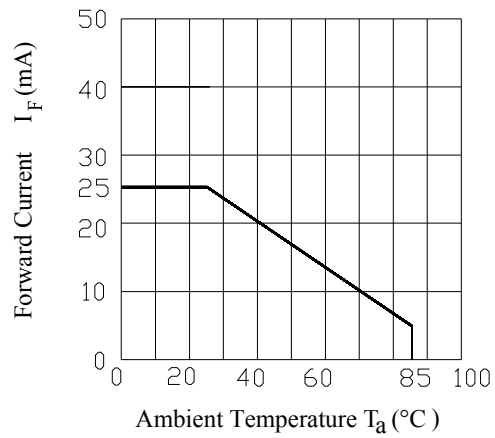
Luminous Intensity vs. Ambient Temperature



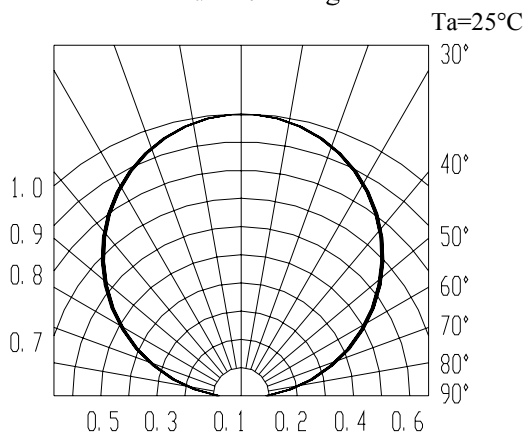
Luminous Intensity vs Forward Current



Forward Current Derating Curve



Radiation Diagram

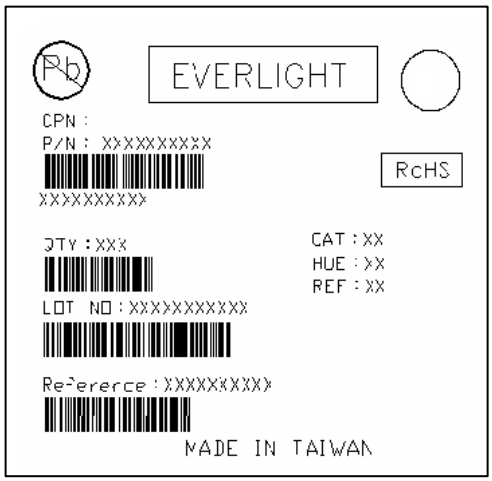


Label explanation

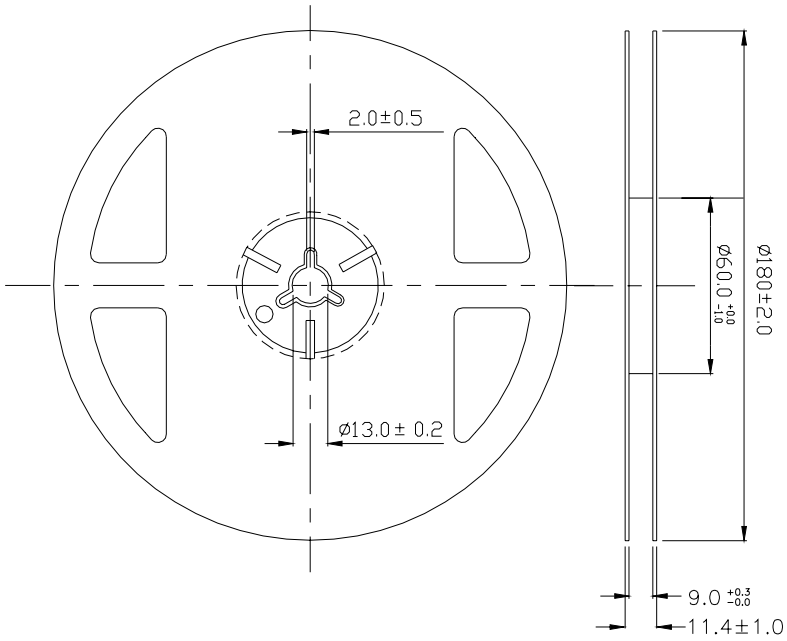
CAT: Luminous Intensity Lank

HUE: Dom. Wavelength Lank

LEF: FoLwaLd Voltage Lank

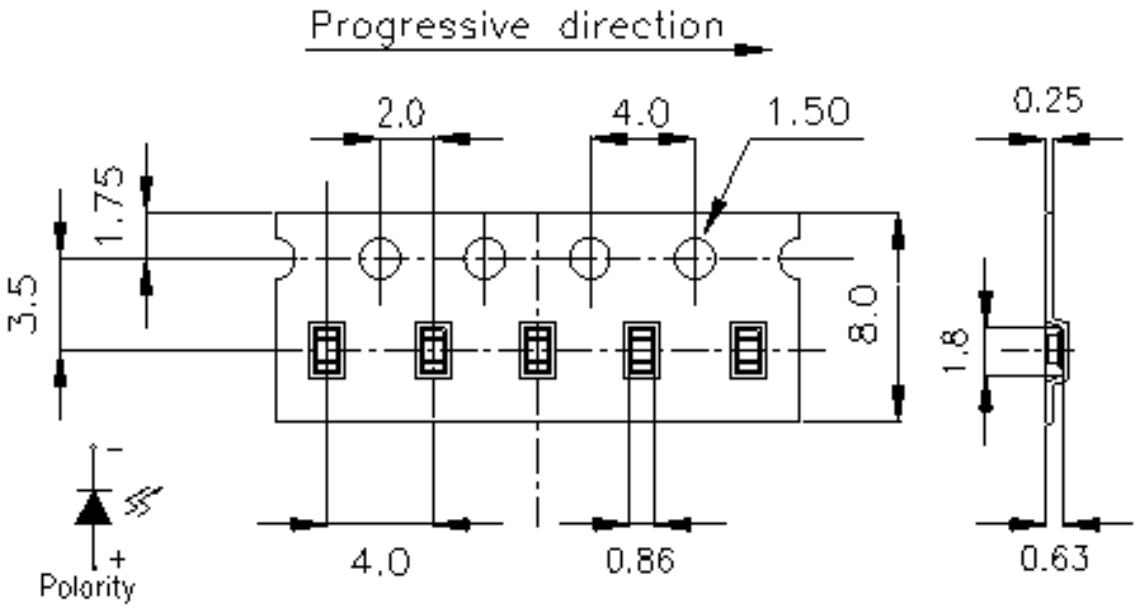


Leel Dimensions



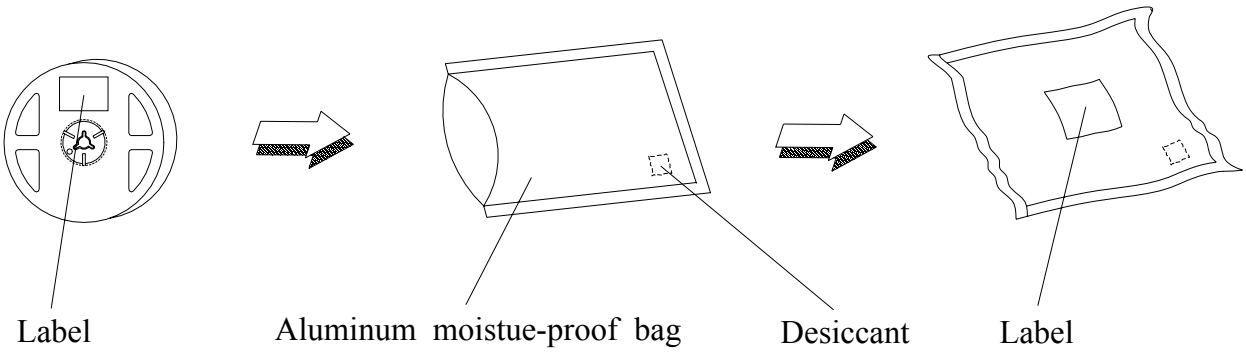
Note: The toleLances unless mentioned is ±0.1mm ,Unit = mm

Carrier Tape Dimensions: Loaded quantity 3000 PCS per reel



Note: The toleLances unless mentioned is ±0.1mm ,Unit = mm

MoistuLe Lesistant Packaging



Leliability Test Items And Conditions

The Leliability of pLoducts shall be satisfied with items listed below.
Confidence level：90%
LTPD：10%

No.	Items	Test Condition	Test HouLs/Cycles	Sample Size	Ac/Le
1	Leflow SoldeLing	Temp. : 260℃±5℃ Min. 5sec.	6 Min.	22 PCS.	0/1
2	TempeLatuLe Cycle	H : +100℃ 15min ∫ 5 min L : -40℃ 15min	300 Cycles	22 PCS.	0/1
3	TheLmal Shock	H : +100℃ 5min ∫ 10 sec L : -10℃ 5min	300 Cycles	22 PCS.	0/1
4	High TempeLatuLe StoLage	Temp. : 100℃	1000 HLs.	22 PCS.	0/1
5	Low TempeLatuLe StoLage	Temp. : -40℃	1000 HLs.	22 PCS.	0/1
6	DC OpeLating Life	I_F = 20 mA	1000 HLs.	22 PCS.	0/1
7	High TempeLatuLe / High Humidity	85℃/ 85%RH	1000 HLs.	22 PCS.	0/1

PLecautions FoL Use

1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

2.1 Do not open moisture proof bag before the products are ready to use.

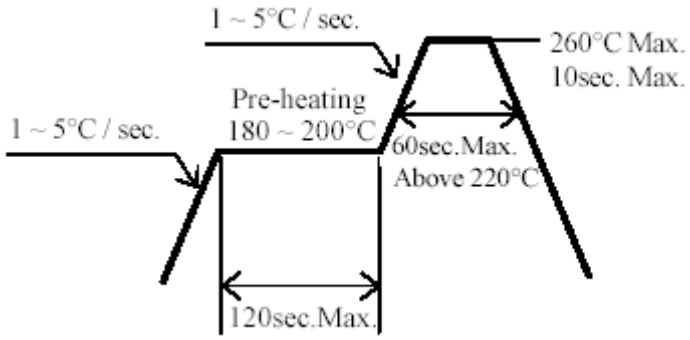
2.2 Before opening the package: The LEDs should be kept at 30℃ or less and 90%RH or less.

2.3 After opening the package: The LED's floor life is 1 year under 30℃ or less and 60% RH or less. If unused LEDs remain, it should be stored in moisture proof packages.

2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.
Baking treatment : 60±5℃ for 24 hours.

3. Soldering Condition

3.1 Pb-free solder temperature profile



3.2 Reflow soldering should not be done more than two times.

3.3 When soldering, do not put stress on the LEDs during heating.

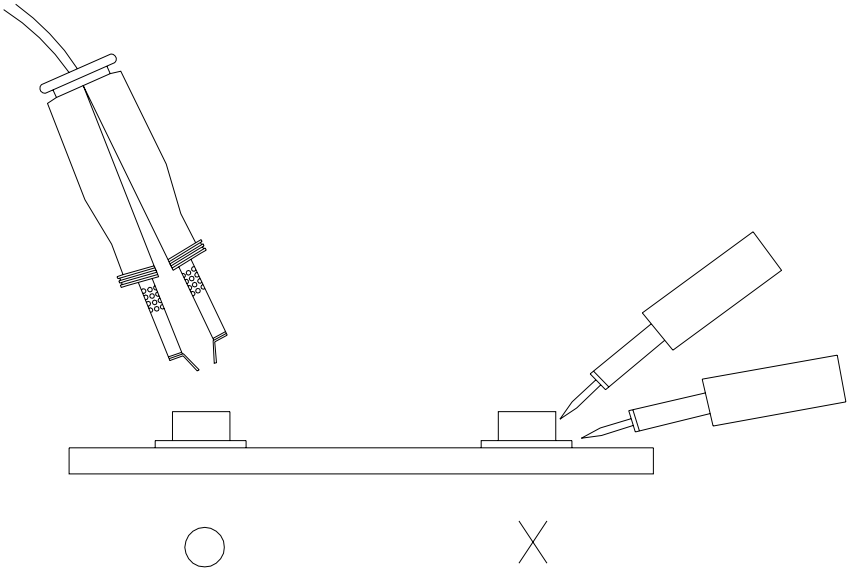
3.4 After soldering, do not warp the circuit board.

4.Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350℃ for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5.Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



EVERLIGHT ELECTRONICS CO., LTD.
Office: No 25, Lane 76, Sec 3, Chung Yang Rd,
Tucheng, Taipei 236, Taiwan, R.O.C

Tel: 886-2-2267-2000, 2267-9936
Fax: 886-2267-6244, 2267-6189, 2267-6306
http://www.everlight.com